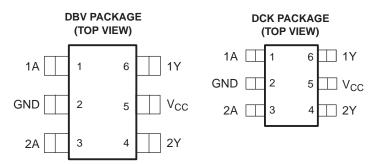




FEATURES

- Qualification in Accordance With AEC-Q100 (1)
- Qualified for Automotive Applications
- Customer-Specific Configuration Control Can Be Supported Along With Major-Change Approval
- Supports 5-V V_{CC} Operation
- Inputs Accept Voltages to 5.5 V
- Max t_{pd} of 5.4 ns at 3.3 V
- Low Power Consumption, 10-μA Max I_{CC}
- ±24-mA Output Drive at 3.3 V
- Contact factory for details. Q100 qualification data available on request.

- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_Δ = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 >2 V at V_{CC} = 3.3 V, T_A = 25°C
- I_{off} Feature Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 1000-V Charged-Device Model (C101)



See mechanical drawings for dimensions.

DESCRIPTION/ORDERING INFORMATION

This dual Schmitt-trigger inverter is designed for 1.65-V to 5.5-V V_{CC} operation.

The SN74LVC2G14 contains two inverters and performs the Boolean function $Y = \overline{A}$. The device functions as two independent inverters, but because of Schmitt action, it may have different input threshold levels for positive-going (V_{T_+}) and negative-going (V_{T_-}) signals.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

ORDERING INFORMATION

T _A	PACKAGE	(1)	ORDERABLE PART NUMBER	TOP-SIDE MARKING(2)
40°C to 95°C	SOT (SOT-23) - DBV	Tape and reel	SN74LVC2G14IDBVRQ1	C14_
–40°C to 85°C	SOT (SC-70) - DCK	Tape and reel	SN74LVC2G14IDCKRQ1	CF_

⁽¹⁾ Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (EACH INVERTER)

INPUT A	OUTPUT Y
Н	L
L	Н

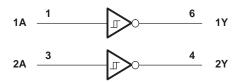


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

⁽²⁾ DBV/DCK: The actual top-side marking has one additional character that designates the assembly/test site.



LOGIC DIAGRAM (POSITIVE LOGIC)



Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range	-0.5	6.5	V	
VI	Input voltage range (2)		-0.5	6.5	V
Vo	Voltage range applied to any output in the high-impedance or p	-0.5	6.5	V	
Vo	Voltage range applied to any output in the high or low state (2)(3	-0.5	V _{CC} + 0.5	V	
I _{IK}	Input clamp current	V _I < 0		-50	mA
I _{OK}	Output clamp current	V _O < 0		- 50	mA
Io	Continuous output current			±50	mA
	Continuous current through V _{CC} or GND			±100	mA
0	Package thermal impedance ⁽⁴⁾	DBV package		165	°C/W
θ_{JA}	гаскаде шеппантречансе	DCK package		259	C/VV
T _{stg}	Storage temperature range	-65	150	°C	

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

Recommended Operating Conditions(1)

			MIN	MAX	UNIT	
V	Cupality voltage	Operating	1.65	5.5	V	
V_{CC}	Supply voltage	ge Data retention only			V	
VI	Input voltage		0	5.5	V	
Vo	Output voltage		0	V_{CC}	V	
ІОН		V _{CC} = 1.65 V		-4		
	$V_{CC} = 2.3 \text{ V}$ High-level output current	V _{CC} = 2.3 V		-8		
		V 2V		-16	mA	
		V _{CC} = 3 V		-24		
		V _{CC} = 4.5 V		-32		
		V _{CC} = 1.65 V		4		
		V _{CC} = 2.3 V		8		
I _{OL}	Low-level output current	V 2V		16	mA	
	$V_{CC} = 3 \text{ V}$			24		
		V _{CC} = 4.5 V		32		
T _A	Operating free-air temperature		-40	85	°C	

⁽¹⁾ All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

 ⁽³⁾ The value of V_{CC} is provided in the recommended operating conditions table.
 (4) The package thermal impedance is calculated in accordance with JESD 51-7.



Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{cc}	MIN	TYP ⁽¹⁾ MAX	UNIT
		1.65 V	0.7	1.4	
V_{T+}		2.3 V	1	1.7	
Positive-going		3 V	1.3	2.2	V
input threshold voltage		4.5 V	1.9	3.1	
		5.5 V	2.2	3.7	
		1.65 V	0.3	0.7	
V_{T-}		2.3 V	0.4	1	
Negative-going		3 V	0.6	1.3	V
input threshold voltage		4.5 V	1.1	2	
		5.5 V	1.4	2.5	
		1.65 V	0.3	8.0	
ΔV_{T}		2.3 V	0.4	0.9	
Hysteresis		3 V	0.4	1.1	V
$(V_{T+} - V_{T-})$		4.5 V	0.6	1.3	
		1.4			
	$I_{OH} = -100 \mu A$	1.65 V to 4.5 V	V _{CC} - 0.1		
	$I_{OH} = -4 \text{ mA}$	1.65 V	1.2		
	$I_{OH} = -8 \text{ mA}$	2.3 V	1.9		V
V _{OH}	I _{OH} = -16 mA	2.1/	2.4		V
	I _{OH} = -24 mA	3 V	2.3		
	I _{OH} = -32 mA	4.5 V	3.8		
	I _{OL} = 100 μA	1.65 V to 4.5 V		0.1	
	I _{OL} = 4 mA	1.65 V		0.45	
N/	I _{OL} = 8 mA	2.3 V		0.3	V
V _{OL}	I _{OL} = 16 mA	2.1/		0.4	·
	I _{OL} = 24 mA	3 V		0.55	
	I _{OL} = 32 mA	4.5 V		0.55	
I _I A inputs	V _I = 5.5 V or GND	0 to 5.5 V		±5	μА
I _{off}	V_1 or $V_0 = 5.5 \text{ V}$	0		±10	μΑ
I _{CC}	$V_I = 5.5 \text{ V or GND}, \qquad I_O = 0$	1.65 V to 5.5 V		10	μΑ
Δl _{CC}	One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND	3 V to 5.5 V		500	μΑ
C _i	$V_I = V_{CC}$ or GND	3.3 V		4	pF

⁽¹⁾ All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

SN74LVC2G14-Q1 DUAL SCHMITT-TRIGGER INVERTER

SCES558C-JULY 2004-REVISED SEPTEMBER 2006



Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	ER FROM TO (OUTPUT)		V _{CC} = 1.8 V ± 0.15 V		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 5 V ± 0.5 V		UNIT
	(INFOT)	(001701)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _{pd}	Α	Y	3.9	9.5	1.9	5.7	2	5.4	1.5	4.3	ns

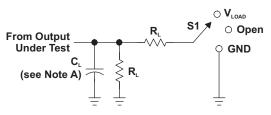
Operating Characteristics

 $T_A = 25^{\circ}C$

PARAMETER		TEST CONDITIONS	V _{CC} = 1.8 V V _{CC} = 2.5		V _{CC} = 3.3 V	V _{CC} = 5 V	UNIT
		TEST CONDITIONS	TYP	TYP	TYP	TYP	UNII
C_{pd}	Power dissipation capacitance	f = 10 MHz	16	17	18	21	pF



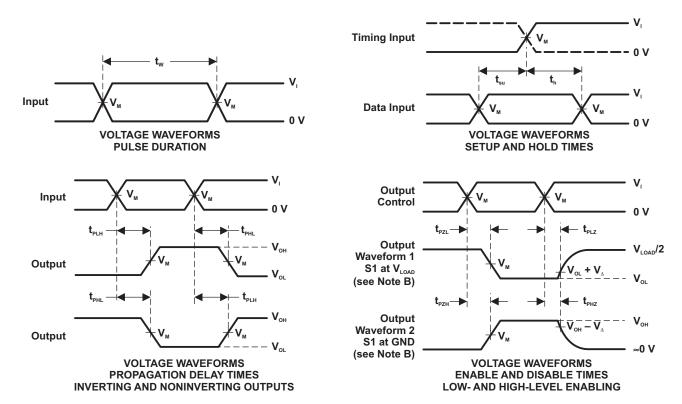
PARAMETER MEASUREMENT INFORMATION



TEST	S1
t _{PLH} /t _{PHL}	Open
t_{PLZ}/t_{PZL}	V _{LOAD}
t _{PHZ} /t _{PZH}	GND

LOAD CIRCUIT

	INPUTS		V	V		Б	V
V _{cc}	V,	t,/t,	V _M	V _{LOAD}	C _L	R _L	V _Δ
1.8 V ± 0.15 V	V _{cc}	≤2 ns	V _{cc} /2	2 × V _{cc}	30 pF	1 k Ω	0.15 V
2.5 V ± 0.2 V	V_{cc}	≤2 ns	V _{cc} /2	2 × V _{cc}	30 pF	500 Ω	0.15 V
3.3 V ± 0.3 V	3 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
5 V ± 0.5 V	V_{cc}	≤2.5 ns	V _{cc} /2	2 × V _{cc}	50 pF	500 Ω	0.3 V



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_o = 50 Ω .
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



PACKAGE OPTION ADDENDUM

5-Apr-2006

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins I	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LVC2G14IDCKRQ1	ACTIVE	SC70	DCK	6	3000	Pb-Free (RoHS)	NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

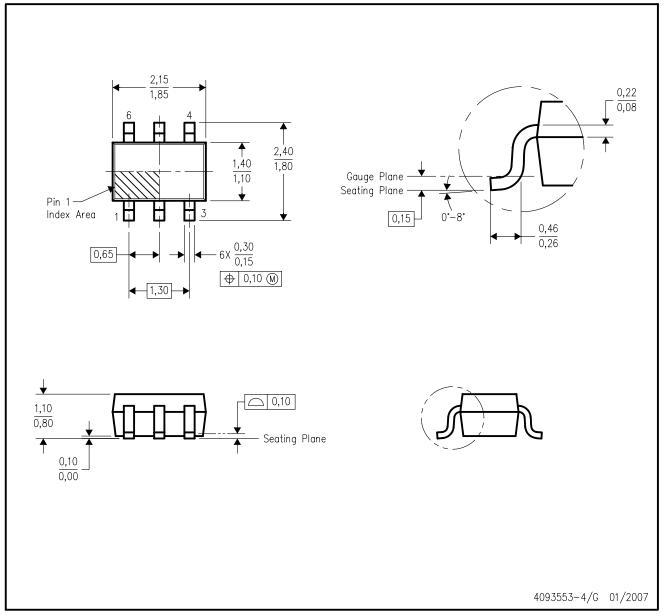
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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DCK (R-PDSO-G6)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Falls within JEDEC MO-203 variation AB.



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